

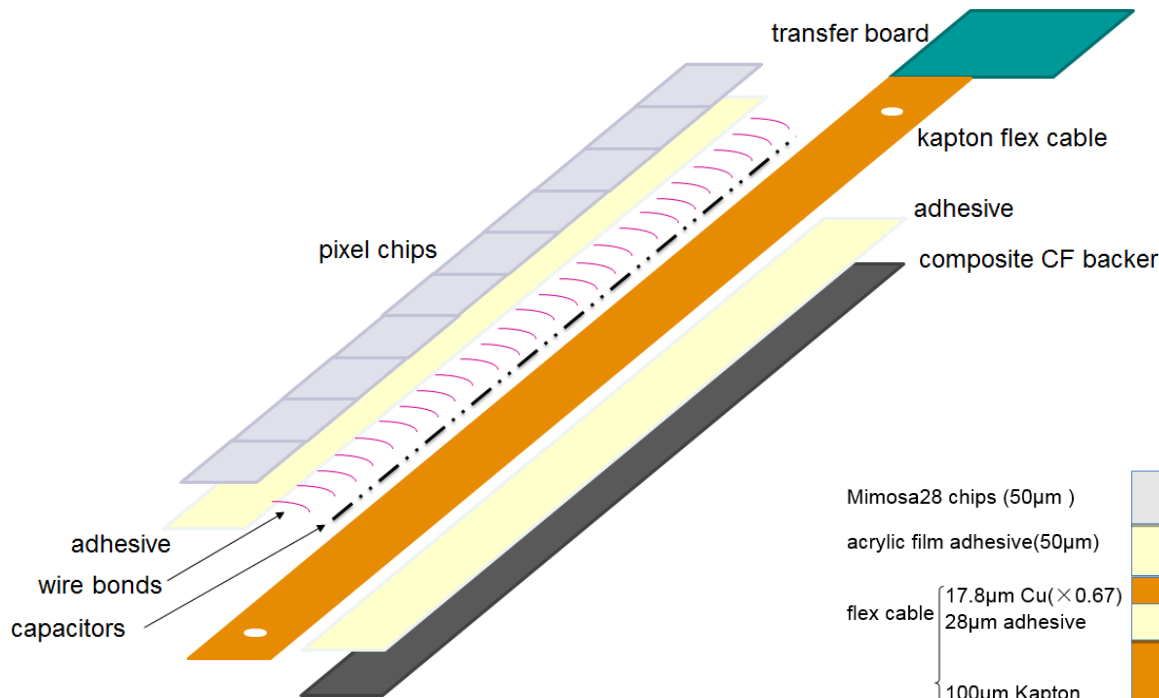
# Module Design for Silicon vertex detector

Mingyi Dong

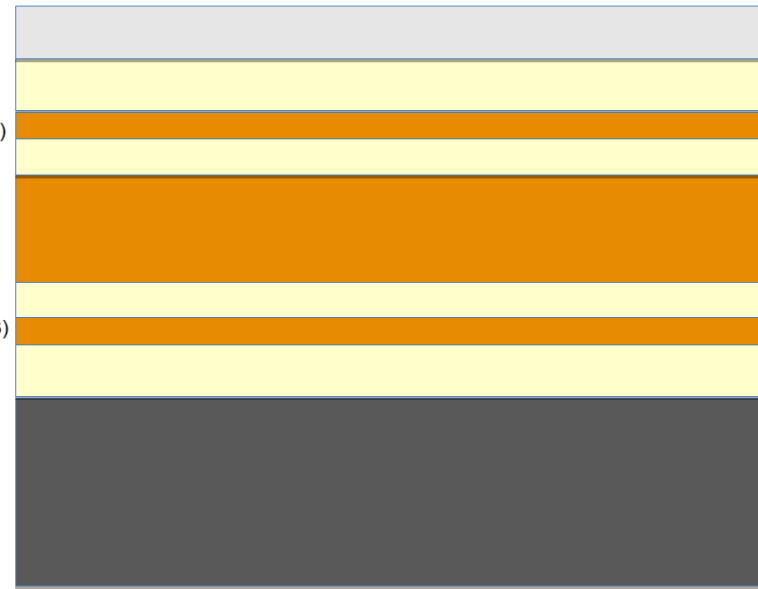
on behalf of the module group

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electronics

# Single-sided Ladder Design

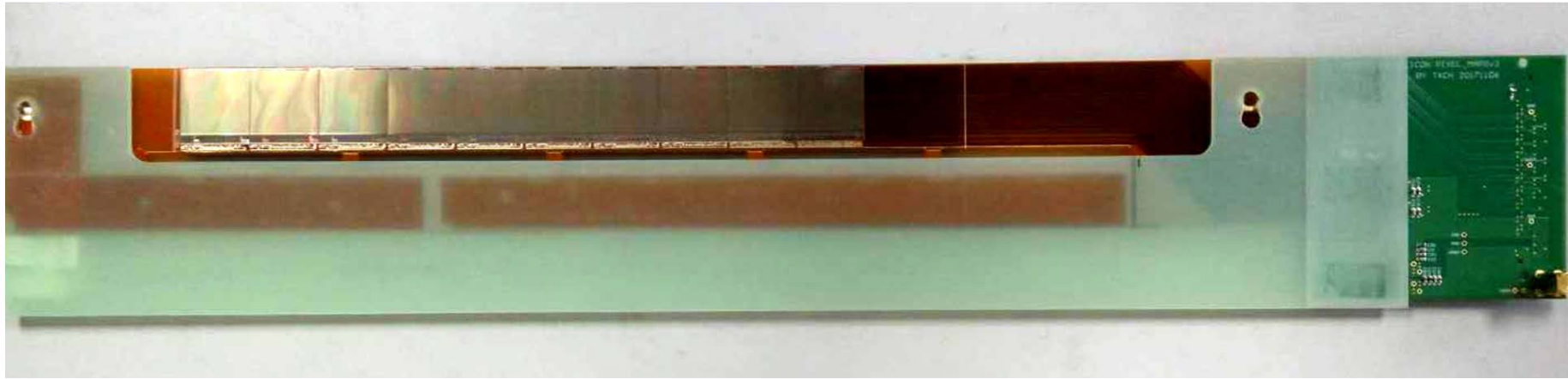


Mimosa28 chips (50 $\mu$ m)  
 acrylic film adhesive(50 $\mu$ m)  
 flex cable { 17.8 $\mu$ m Cu( $\times$ 0.67)  
 28 $\mu$ m adhesive  
 100 $\mu$ m Kapton  
 28 $\mu$ m adhesive  
 17.8 $\mu$ m Cu( $\times$ 0.23)  
 acrylic film adhesive(50 $\mu$ m)  
 sandwich support structure:  
 carbon fiber plate and  
 PMI foam (equivalent  
 thickness: 350 $\mu$ m CF)

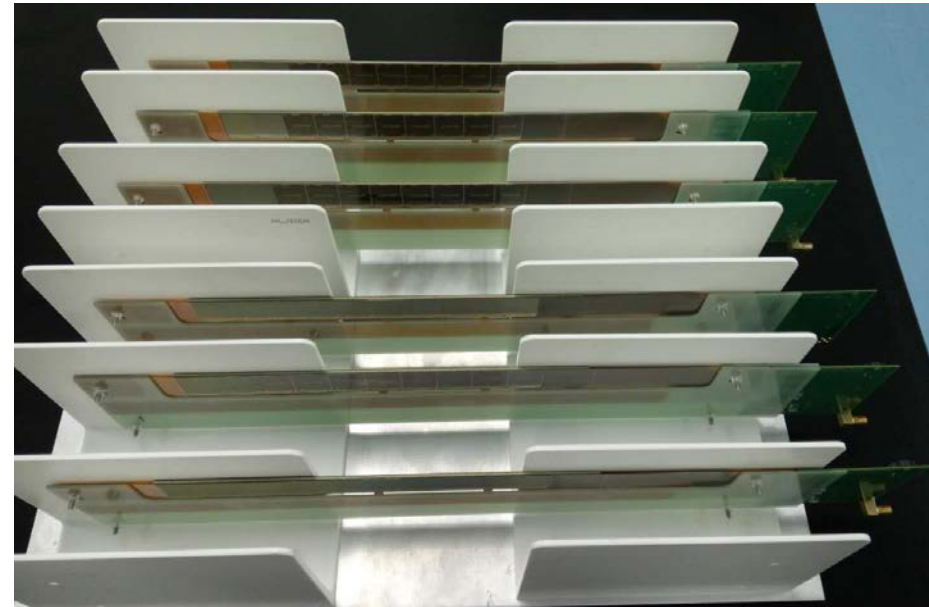


- Ladder: basic building and functional block of the detector, key issue for the prototype
  - 10 Mimosa28 chips (50 $\mu$ m)
  - Flex cable
  - Carbon fiber mechanical support

# Ladder Assembly

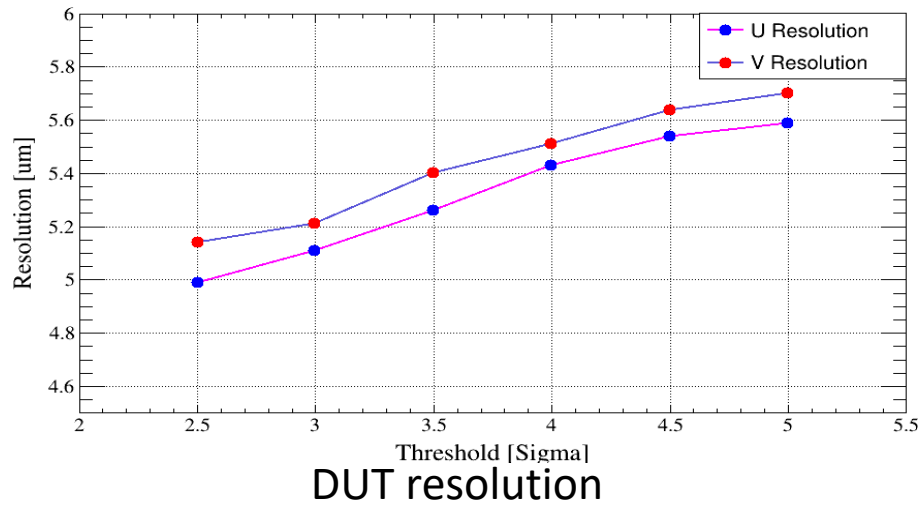


- Material budget of the ladder by calculation:  $0.37\% X_0$  /ladder
- Chip location accuracy measured by imaging machine:  $< 10\mu\text{m}$
- Ladder assembly was operated at a dedicated jigs to ensure the location accuracy of the chips

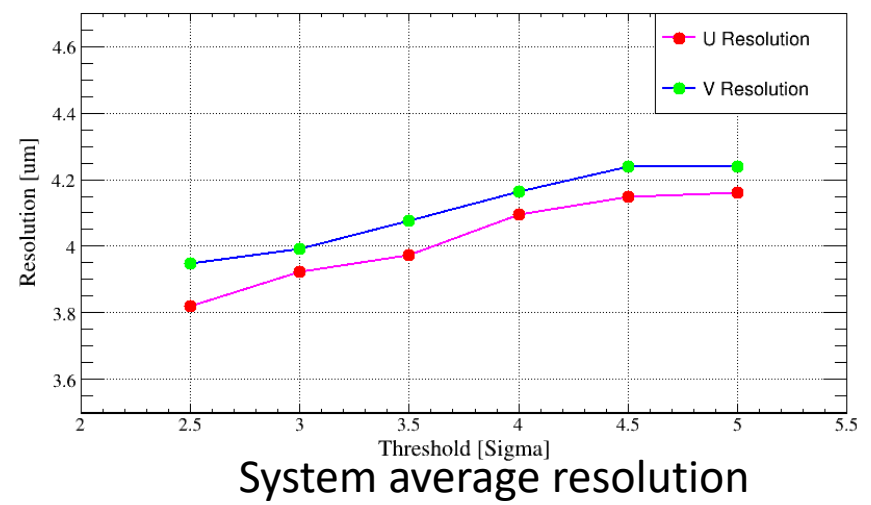


# Spatial Resolution

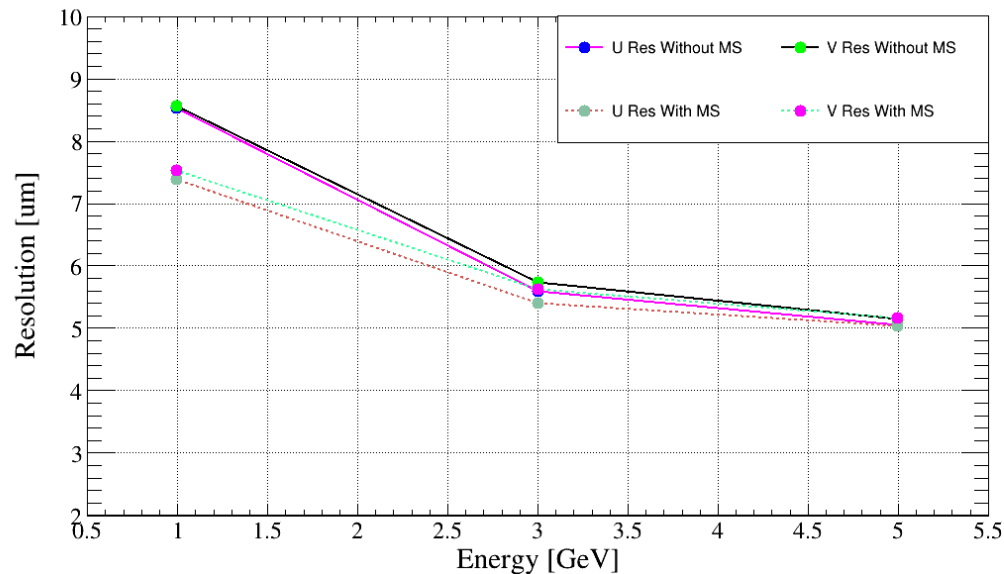
Resolution VS Threshold @ 5GeV



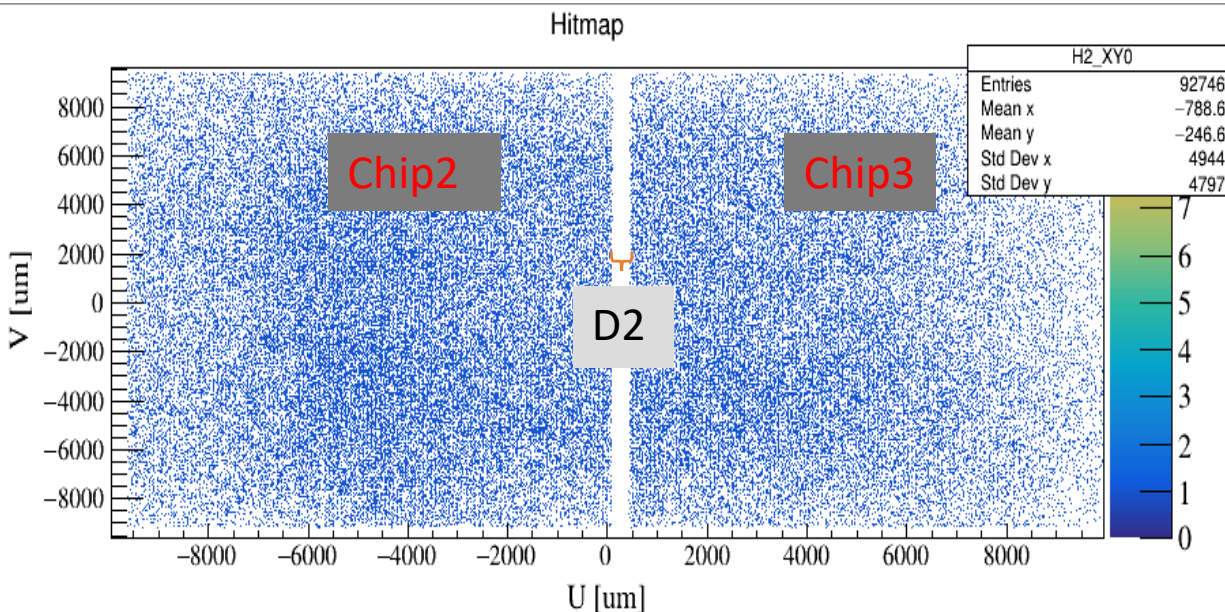
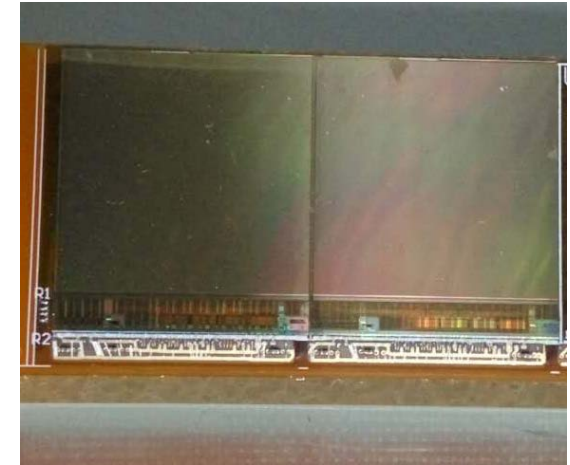
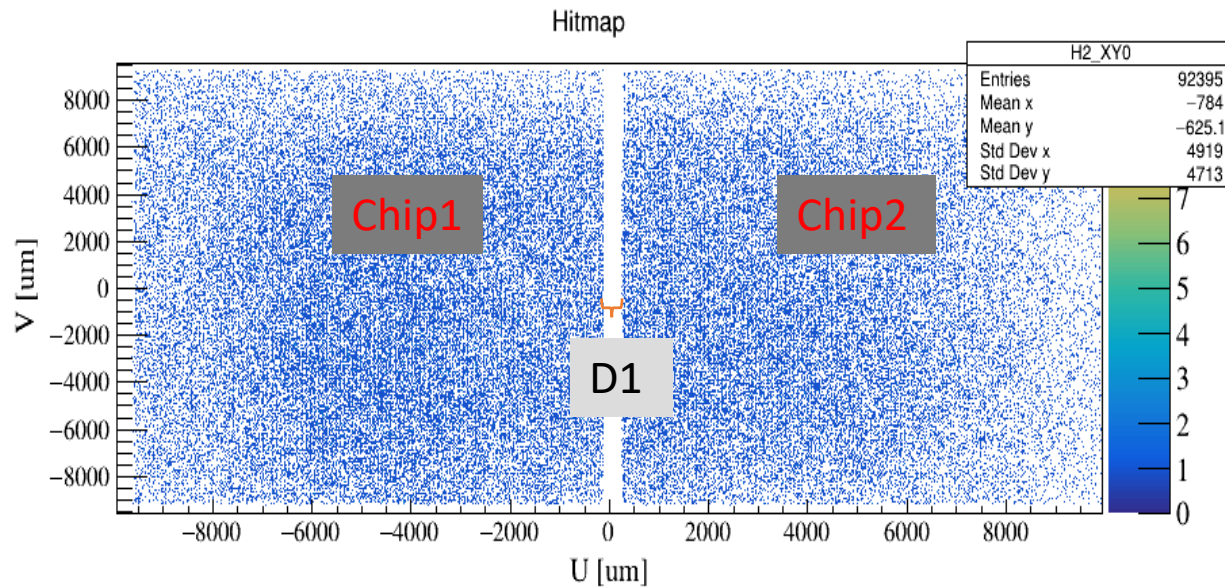
Resolution VS Threshold @ 5GeV



Spatial Resolution VS Energy @  $2.5\sigma$

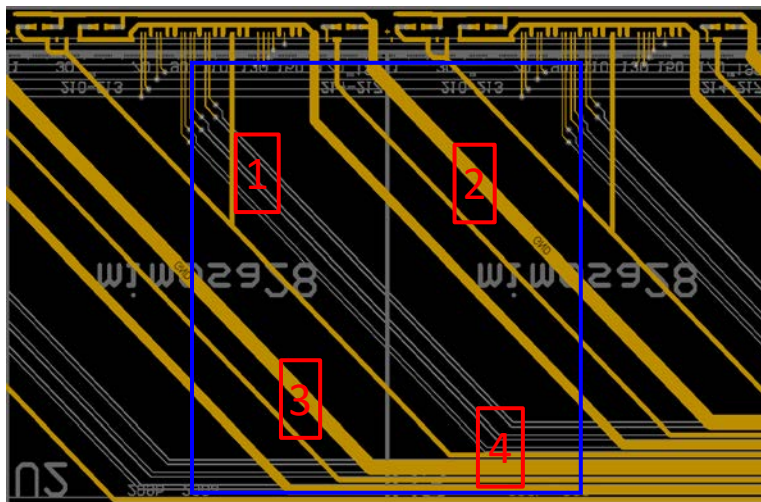
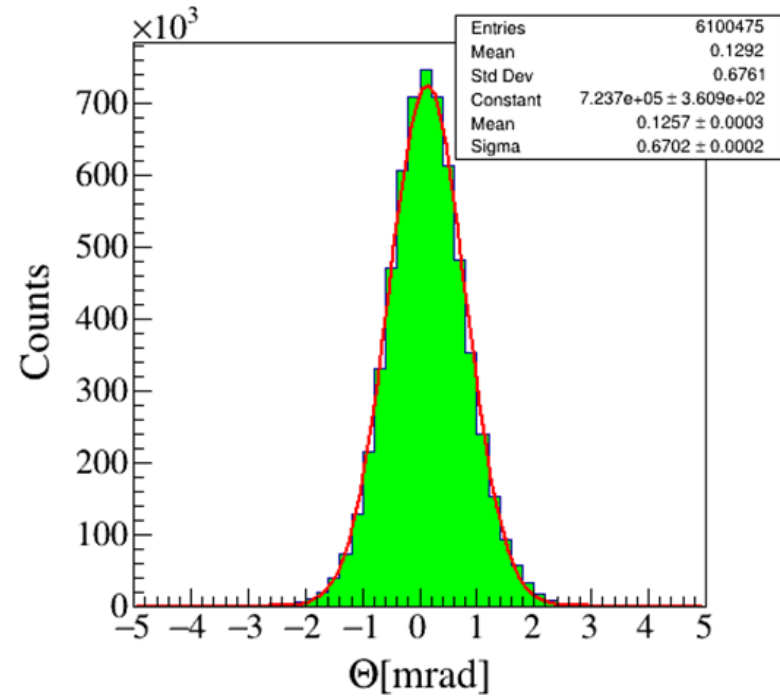
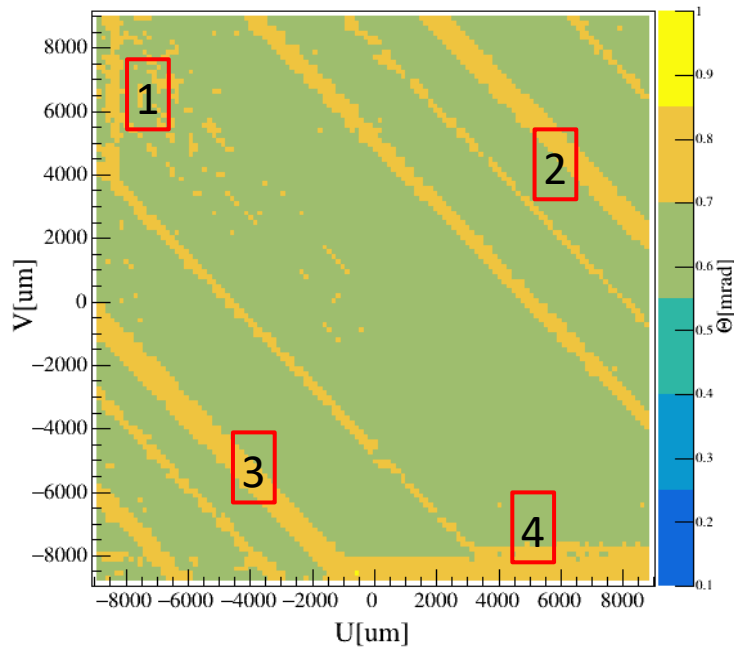


# Gap between two chips



- $D1 \approx D2 \approx 340 \mu\text{m}$
- Average gap between neighboring chips is  $340 \mu\text{m}$
- Take into account the row sequencer on the chip, chip location accuracy is better than  $10 \mu\text{m}$

# Material budget

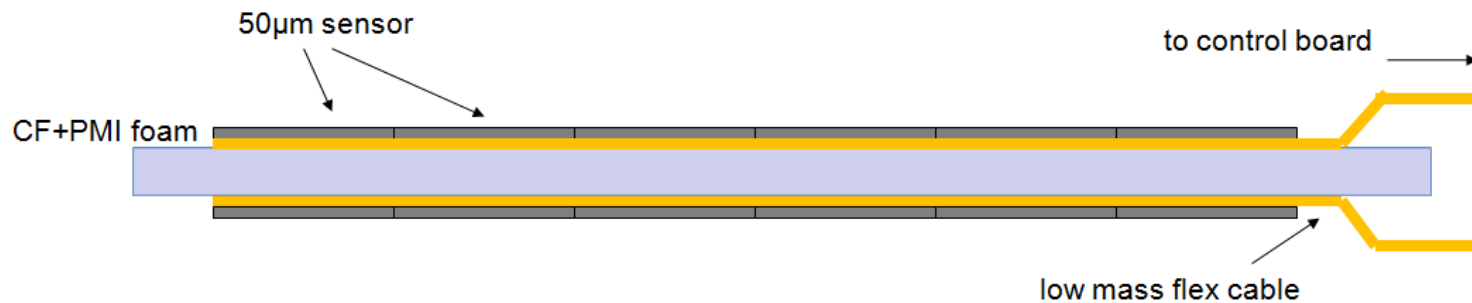
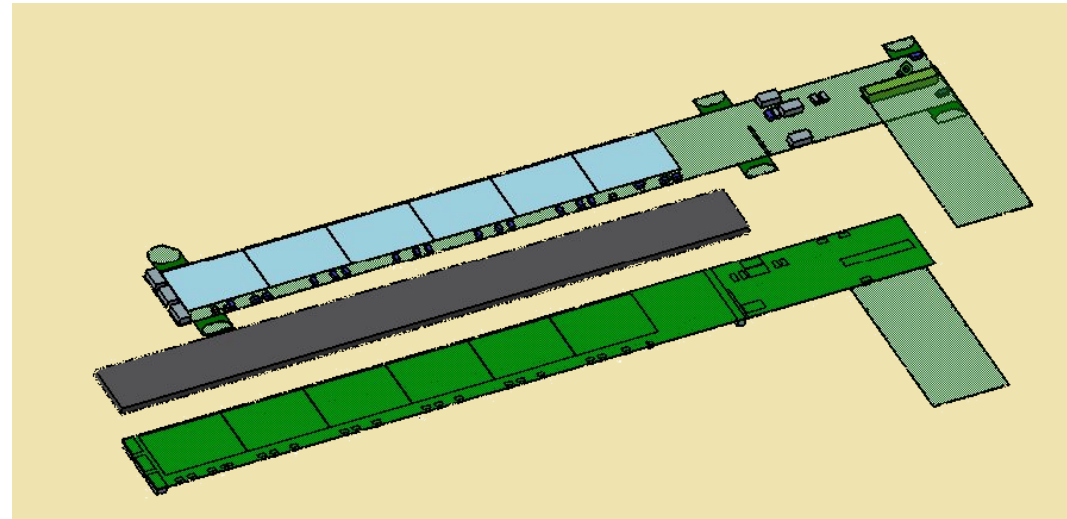
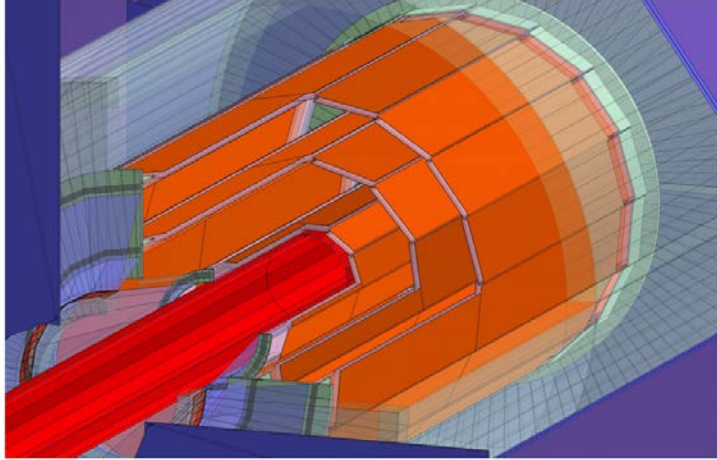


$$\theta_0 = \frac{13.6 \text{ MeV}}{\beta c p} Z \sqrt{\frac{x}{X_0}} \left( 1 + 0.038 \ln \left( \frac{x}{X_0} \right) \right) \left. \vphantom{\theta_0} \right\} \frac{x}{X_0} = 0.39\%$$

$\theta_0 = 0.0006702 \text{ rad}$   
 $P = 1 \text{ GeV}$

- Be consistent with the calculation result

# Double-sided ladder concepts



- Single-sided ladder → Double sided ladder (CEPC vertex R&D)
- Why Double-sided? Has features attractive: low material budget (two layers share one support), high rigidness, high resolution

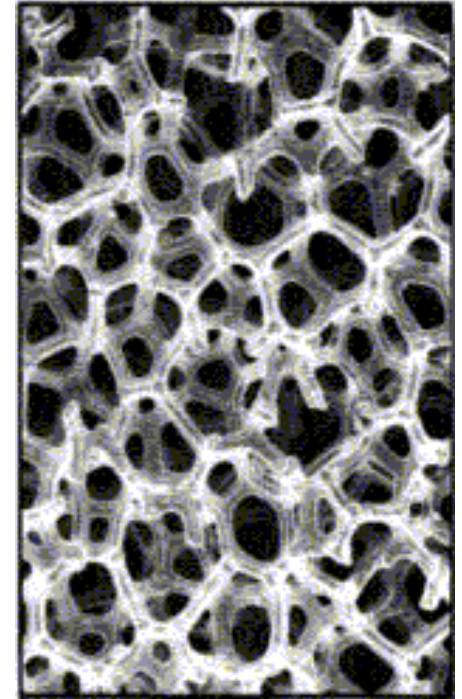
# Double-sided ladder design



- Material budget: 0.48%  $X_0$  (flex cable with copper traces )
- Reduce to 0.29%  $X_0$  if using aluminum traces



# Carbon Fiber support

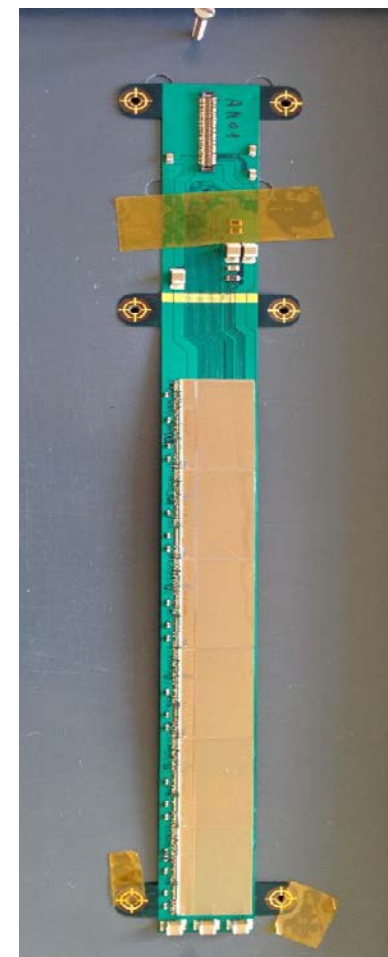
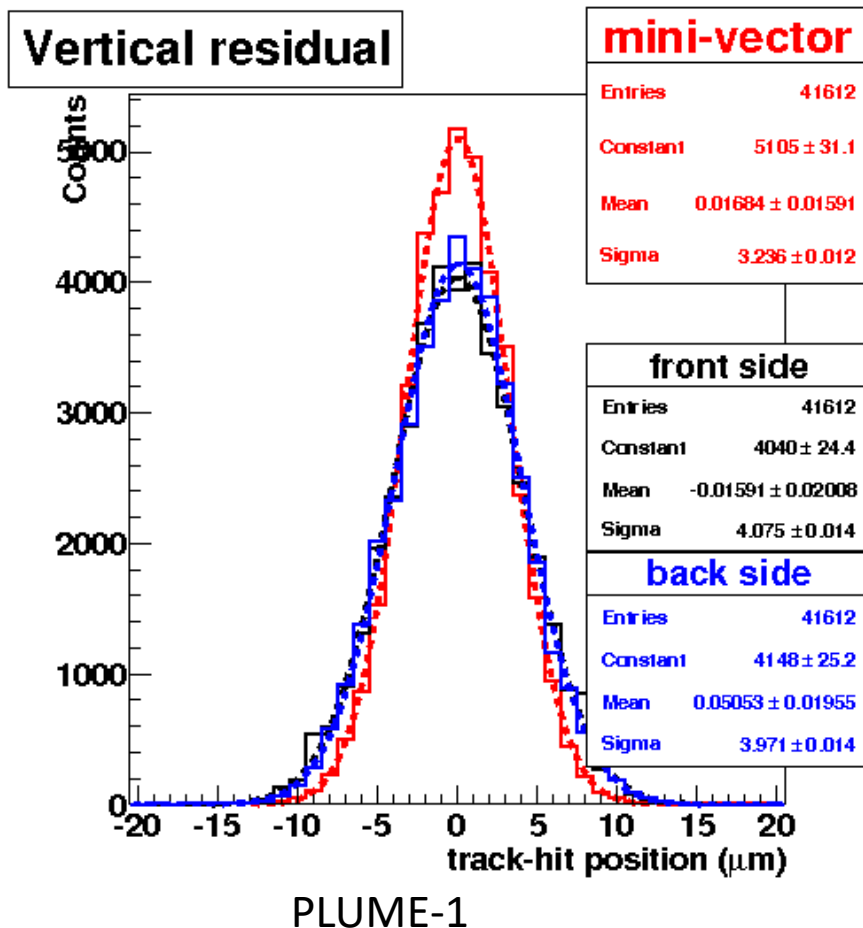


- Sandwich structure : CF(150 $\mu$ m) + Foam (1.5mm) + CF (150 $\mu$ m)
- Optimization of the material and thickness
  - foam with different material and different fill factor (8%-4%)
  - CF with different elasticity modulus

# Assembly

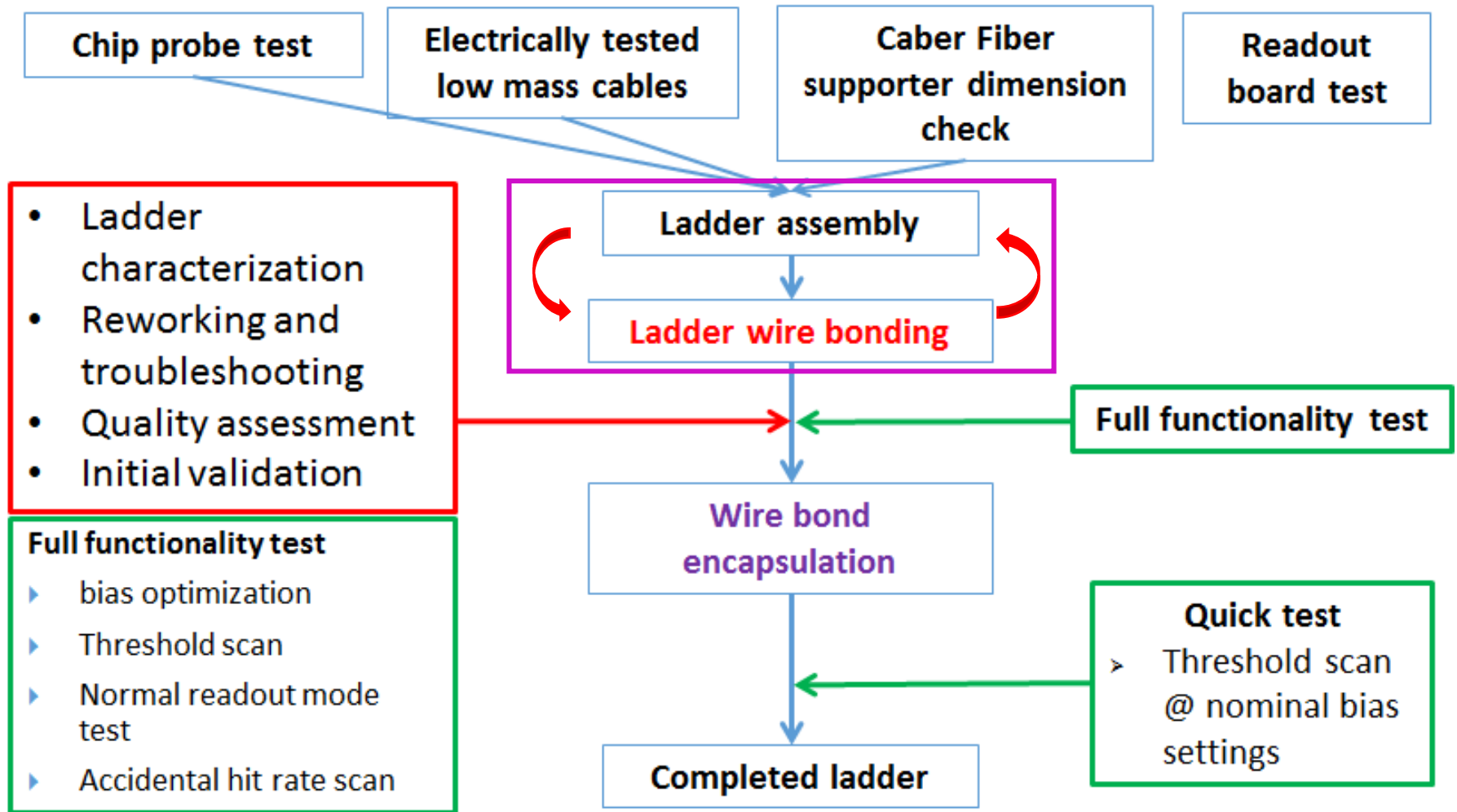
- Step 1
  - Aligning & gluing sensors to flex cables
  - Using automatic placement machine
- Step 2
  - Wire bonding between chips and flex cable on individual flex cable
  - To get 2 individual single-sided ladders
- Step 3
  - Gluing 2 modules on both sides of a CF fiber support
  - Operating manually with a dedicated jigs

# PLUME ladder



- Material budget of PLUME-1 ladder (Cross section)  $\sim (0.47 \pm 0.02) \% X_0$

# Key procedure of ladder development



*Thanks for your attention !*